



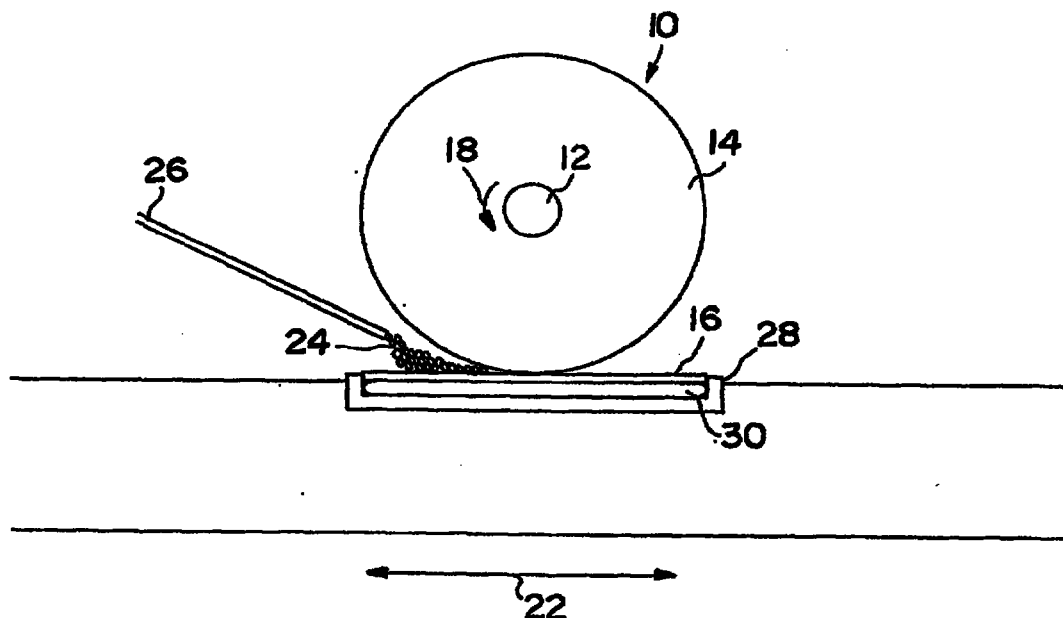
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(54) Title: **CHEMICAL MECHANICAL PLANARIZATION TOOL HAVING A LINEAR POLISHING ROLLER**



(57) Abstract

A tool (10) is provided for polishing, planarizing, cleaning or otherwise processing silicon wafers (16) or other workpieces. It comprises a cylindrical roller (14) mounted on a spindle (12) above a platform or workstation on which a wafer is mounted. The roller (14) is movable into and out of contact with the wafer (16) and is rotatable to polish the wafer (16). The wafer (16) may also be rotatable and translatable on the platform. The roller (14) has a linear region of contact with the wafer (16) during processing operations.